

HD6301V0, HD63A01V0, HD63B01V0 CMOS MCU (Microcomputer Unit)

—PRELIMINARY—

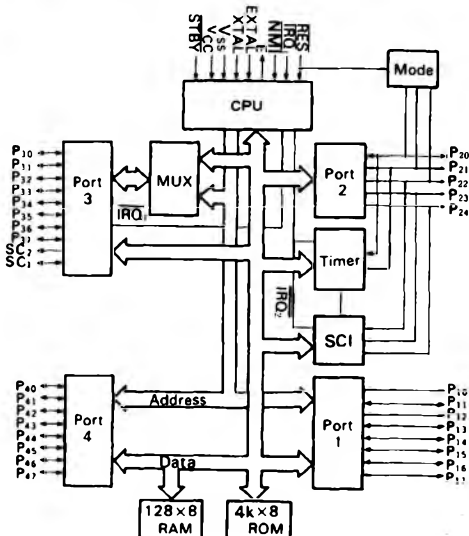
The HD6301V0 is an 8-bit CMOS single-chip microcomputer unit, Object Code compatible with the HD6801. 4kB ROM, 128 bytes RAM, Serial Communication Interface (SCI), parallel I/O terminals as well as three functions of timer on chip are incorporated in the HD6301V0. It is bus compatible with HMCS6800, provided with some additional functions such as an improved execution time of key instruction plus several new instructions of operation to increase system throughput. The HD6301V0 can be expanded up to 65k words. Like the HMCS6800 family, I/O level is TTL compatible with +5.0V single power supply. By using the Hitachi's 3 μ m CMOS process, low power consumption is realized. And as lower power dissipation mode, HD6301V0 has Sleep Mode and Stand-By Mode. So flexible low power consumption application is possible.

■ FEATURES

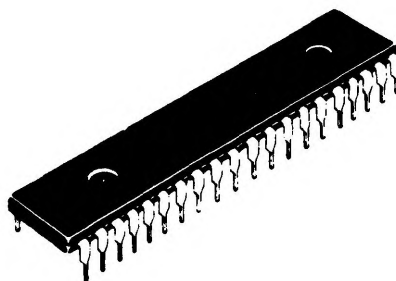
- Object Code Upward Compatible with HD6801 Family
- Abundant On-Chip Functions Compatible with HD6801V0; 4kB ROM, 128 Bytes RAM, 29 Parallel I/O Lines, 2 Lines of Data Strobe, 16-bit Timer, Serial Communication Interface
- Low Power Consumption Mode: Sleep Mode, Standby Mode
- Minimum Instruction Cycle Time
1 μ s (f=1MHz), 0.67 μ s (f=1.5MHz), 0.5 μ s (f=2MHz)
- Bit Manipulation, Bit Test Instruction
- Protection from System Burst: Address Trap, Op-Code Trap
- Up to 65k Words Address Space
- Wide Operation Range

V_{CC} =3 to 6V (f=0.5MHz), f=0.1 to 1.5MHz (V_{CC} =5V \pm 10%), f=0.1 to 2.0MHz (V_{CC} =5V \pm 5%)

■ BLOCK DIAGRAM

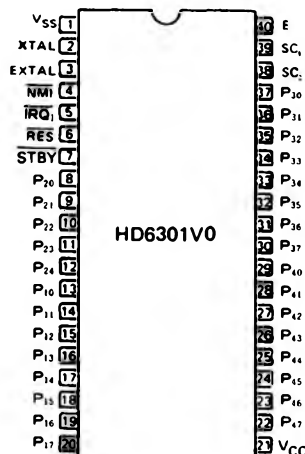


HD6301V0P, HD63A01V0P, HD63B01V0P



(DP-40)

■ PIN ARRANGEMENT



(Top View)

■ TYPE OF PRODUCTS

Type No.	Bus Timing
HD6301V0	1 MHz
HD63A01V0	1.5 MHz
HD63B01V0	2 MHz

■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V_{CC}	-0.3 ~ +7.0	V
Input Voltage	V_{in}	-0.3 ~ $V_{CC}+0.3$	V
Operating Temperature	T_{opr}	0 ~ +70	°C
Storage Temperature	T_{stg}	-55 ~ +150	°C

(NOTE) This product has protection circuits in input terminal from high static electricity voltage and high electric field. But be careful not to apply overvoltage more than maximum ratings to these high input impedance protection circuits. To assure the normal operation, we recommend $V_{in}, V_{out} : V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$.

■ ELECTRICAL CHARACTERISTICS

- DC CHARACTERISTICS ($V_{CC} = 5.0V \pm 10\%$ --- $f = 1.0 \sim 1.5MHz$, $V_{CC} = 5.0V \pm 5\%$ --- $f = 2.0MHz$, $V_{SS} = 0V$, $T_a = 0 \sim +70^\circ C$, unless otherwise noted.)

Item	Symbol	Test Condition	min	typ	max	Unit
Input "High" Voltage	RES, STBY	V_{IH}	$V_{CC}-0.5$	—	$V_{CC}+0.3$	V
	EXTAL		$V_{CC} \times 0.7$	—		
	Other Inputs		2.0	—		
Input "Low" Voltage	All Inputs	V_{IL}	-0.3	—	0.8	V
Input Leakage Current	NMI, $\overline{IRQ_1}$, RES, STBY	$ I_{in} $	$V_{in} = 0.4 \sim 5.1V$	—	—	1.0 μA
Three State (off-state) Leakage Current	$P_{10} \sim P_{17}$, $P_{20} \sim P_{24}$, $P_{30} \sim P_{37}$, $P_{40} \sim P_{47}$, $\overline{IS3}$	$ I_{TSI} $	$V_{in} = 0.4 \sim 5.1V$	—	—	1.0 μA
Output "High" Voltage	All Outputs	V_{OH}	$I_{OH} = -200\mu A$	2.4	—	V
			$I_{OH} = -10\mu A$	$V_{CC}-0.7$	—	V
Output "Low" Voltage	All Outputs	V_{OL}	$I_{OL} = 1.6mA$	—	—	0.55 V
Input Capacitance	All Inputs	C_{in}	$V_{in}=0V, f=1.0MHz, T_a=25^\circ C$	—	—	12.5 pF
Standby Current	Non Operation	I_{CC}		—	2.0	15.0 μA
Current Dissipation*		I_{CC}	Operating ($f=1MHz^{**}$)	—	6.0	10.0 mA
			Sleeping ($f=1MHz^{**}$)	—	1.0	2.0
RAM Stand-By Voltage		V_{RAM}		2.0	—	V

* $V_{IH} \text{ min} = V_{CC}-1.0V, V_{IL} \text{ max} = 0.8V$

** Current Dissipation of the operating or sleeping condition is proportional to the operating frequency. So the typ. or max. values about Current Dissipations of the when of $f = x$ MHz operation are decided according to the following formula;

typ. value ($f = x$ MHz) = typ. value ($f = 1MHz$) $\times x$
max. value ($f = x$ MHz) = max. value ($f = 1MHz$) $\times x$
(both the sleeping and operating)

HD6301V0, HD63A01V0, HD63B01V0

- AC CHARACTERISTICS ($V_{CC} = 5.0V \pm 10\%$ --- $f = 1.0 \sim 1.5MHz$, $V_{CC} = 5.0V \pm 5\%$ --- $f = 2.0MHz$, $V_{SS} = 0V$, $T_a = 0 \sim +70^\circ C$, unless otherwise noted.)

BUS TIMING

Item	Symbol	Test Condition	HD6301V0			HD63A01V0			HD63B01V0			Unit
			min	typ	max	min	typ	max	min	typ	max	
Cycle Time	t_{CYC}	Fig. 1 Fig. 2	1	—	10	0.666	—	10	0.5	—	10	μs
Address Strobe Pulse Width "High"	PW_{ASH}		200	—	—	135	—	—	120	—	—	ns
Address Strobe Rise Time	t_{ASr}		—	—	35	—	—	35	—	—	35	ns
Address Strobe Fall Time	t_{ASf}		—	—	35	—	—	35	—	—	35	ns
Address Strobe Delay Time	t_{ASD}		40	—	—	TBD	—	—	TBD	—	—	ns
Enable Rise Time	t_{Er}		—	—	35	—	—	35	—	—	35	ns
Enable Fall Time	t_{Ef}		—	—	35	—	—	35	—	—	35	ns
Enable Pulse Width "High" Level	PW_{EH}		450	—	—	TBD	—	—	TBD	—	—	ns
Enable Pulse Width "Low" Level	PW_{EL}		450	—	—	TBD	—	—	TBD	—	—	ns
Address Strobe to Enable Delay Time	t_{ASED}		60	—	—	TBD	—	—	TBD	—	—	ns
Address Delay Time	t_{AD1}		—	—	250	—	—	TBD	—	—	TBD	ns
	t_{AD2}		—	350	—	—	TBD	—	—	TBD	—	ns
Address Delay Time for Latch	t_{ADL}		—	—	250	—	—	220	—	—	140	ns
Data Set-up Time	Write t_{DSW}	Fig. 2	230	—	—	TBD	—	—	TBD	—	—	ns
	Read t_{DSR}		80	—	—	TBD	—	—	TBD	—	—	ns
Data Hold Time	Read t_{HR}		0	—	—	0	—	—	0	—	—	ns
	Write t_{HW}		20	—	—	20	—	—	20	—	—	ns
Address Set-up Time for Latch	t_{ASL}		60	—	—	TBD	—	—	TBD	—	—	ns
Address Hold Time for Latch	t_{AHL}		20	—	—	TBD	—	—	TBD	—	—	ns
Address Hold Time	t_{AH}		20	—	—	20	—	—	20	—	—	ns
$A_0 \sim A_7$ Set-up Time Before E	t_{ASM}		200	—	—	TBD	—	—	TBD	—	—	ns
Peripheral Read Access Time	Non-Multiplexed Bus (t_{ACCN})		—	—	(635)	—	—	TBD	—	—	TBD	ns
	Multiplexed Bus (t_{ACCM})		—	—	(635)	—	—	TBD	—	—	TBD	ns
Oscillator stabilization Time	t_{RC}	Fig. 10	20	—	—	20	—	—	20	—	—	ms
Processor Control Set-up Time	t_{PCS}	Fig. 11	250	—	—	250	—	—	250	—	—	ns

PERIPHERAL PORT TIMING

Item	Symbol	Test Condition	HD6301V0			HD63A01V0			HD63B01V0			Unit
			min	typ	max	min	typ	max	min	typ	max	
Peripheral Data Set-up Time	Port 1, 2, 3, 4 t_{PDSU}	Fig. 3	200	—	—	200	—	—	200	—	—	ns
Peripheral Data Hold Time	Port 1, 2, 3, 4 t_{PDH}	Fig. 3	200	—	—	200	—	—	200	—	—	ns
Delay Time, Enable Positive Transition to OS3 Negative Transition	t_{OSD1}	Fig. 5	—	—	300	—	—	300	—	—	300	ns
Delay Time, Enable Positive Transition to OS3 Positive Transition	t_{OSD2}	Fig. 5	—	—	300	—	—	300	—	—	300	ns
Delay Time, Enable Negative Transition to Peripheral Data Valid	Port 1, 2*, 3, 4 t_{PWD}	Fig. 4	—	—	300	—	—	300	—	—	300	ns
Input Strobe Pulse Width	t_{PWS}	Fig. 6	200	—	—	200	—	—	200	—	—	ns
Input Data Hold Time	Port 3 t_{IH}	Fig. 6	150	—	—	150	—	—	150	—	—	ns
Input Data Setup Time	Port 3 t_{IS}	Fig. 6	0	—	—	0	—	—	0	—	—	ns

* Except P₂₁

TIMER, SCI TIMING

Item	Symbol	Test Condition	HD6301V0			HD63A01V0			HD63B01V0			Unit
			min	typ	max	min	typ	max	min	typ	max	
Timer Input Pulse Width	t _{PWT}		2.5	—	—	TBD	—	—	TBD	—	—	t _{cyc}
Delay Time, Enable Positive Transition to Timer Out	t _{TOD}	Fig. 7	—	—	400	—	—	400	—	—	400	ns
SCI Input Clock Cycle	t _{Scyc}		2.0	—	—	TBD	—	—	TBD	—	—	μs
SCI Input Clock Pulse Width	t _{PWSCK}		0.4	—	0.6	0.4	—	0.6	0.4	—	0.6	t _{cyc}

MODE PROGRAMMING

Item	Symbol	Test Condition	HD6301V0			HD63A01V0			HD63801V0			Unit
			min	typ	max	min	typ	max	min	typ	max	
RES "Low" Pulse Width	PW _{RSTL}	Fig. 8	3	—	—	3	—	—	3	—	—	t _{cy}
Mode Programming Set-up Time	t _{MPS}		2	—	—	2	—	—	2	—	—	t _{cy}
Mode Programming Hold Time	t _{HMP}		150	—	—	150	—	—	150	—	—	ns

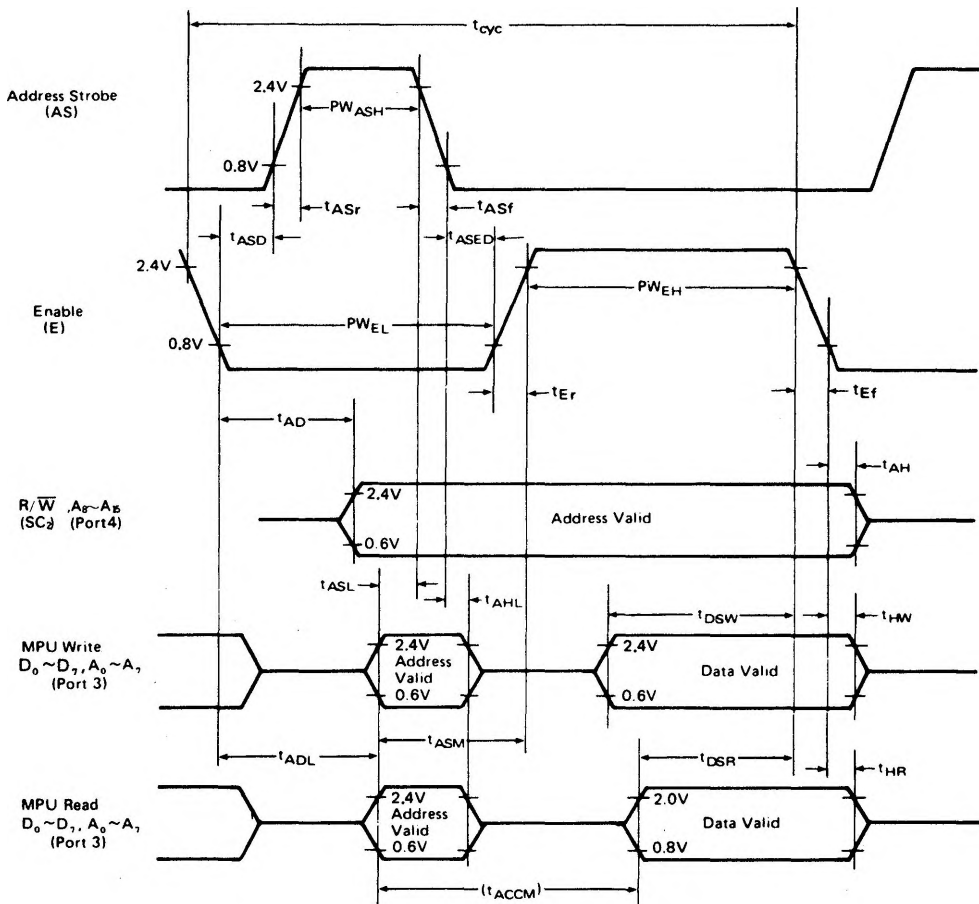


Figure 1 Expanded Multiplexed Bus Timing

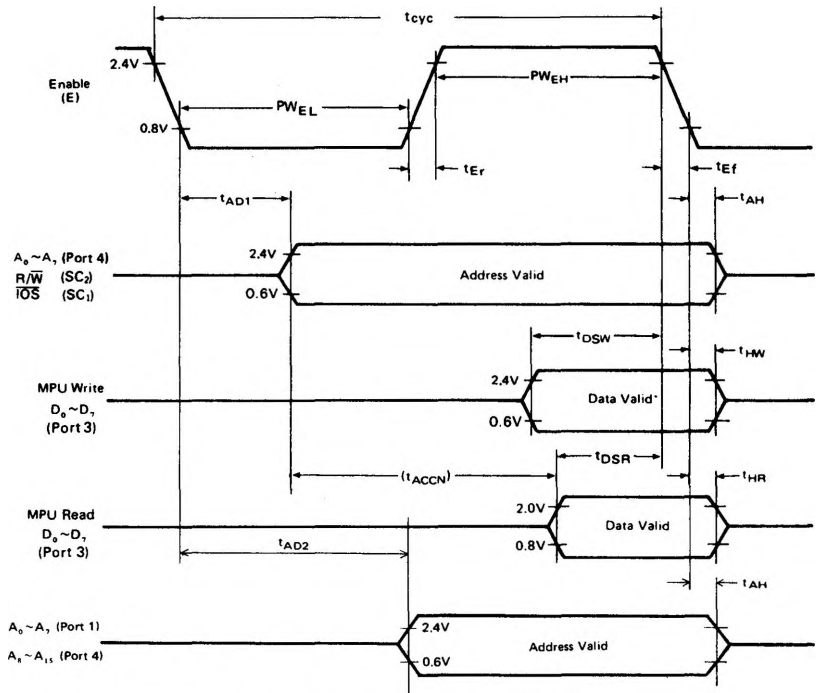
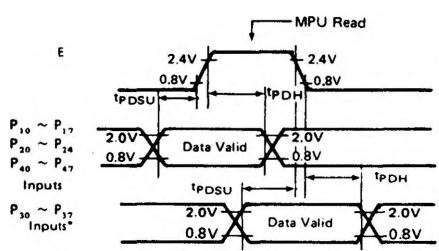
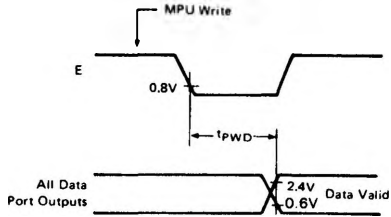


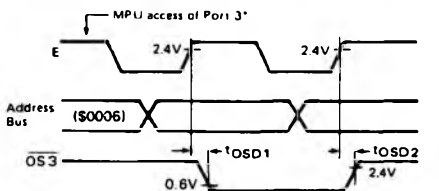
Figure 2 Expanded Non-Multiplexed Bus Timing



*Port 3 Non-Latched Operation
Figure 3 Port Data Set-up and Hold Times (MPU Read)



Note) Port 2: Except P_{2,1}
Figure 4 Port Data Delay Times (MPU Write)



*Access matches Output Strobe Select (OSS = 0, a read; OSS = 1, a write)
Figure 5 Port 3 Output Strobe Timing (Single Chip Mode)

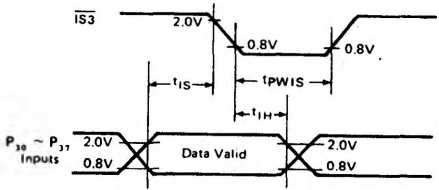


Figure 6 Port 3 Latch Timing (Single Chip Mode)

Figure 7 Timer Output Timing

Figure 8 Mode Programming Timing

Figure 9 Bus Timing Test Loads (TTL Load)

Figure 10 Interrupt Sequence

FUNCTIONAL PIN DESCRIPTION

V_{CC}, V_{SS}

These two pins are used for power supply and GND. Recommended power supply voltage is 5V ± 10% (HD6301V0, HD63A01V0), 5V ± 5% (HD63B01V0) or 3 to 6V other than for high speed operation (500kHz).

XTAL, EXTAL

These two pins are connected with parallel resonant fundamental crystal, AT cut. For instance, in order to obtain the system clock 1MHz, a 4MHz resonant fundamental crystal is useful because the divide by 4 circuitry is included. EXTAL accepts an external clock input of duty 50% (±10%) to drive, then internal clock is a quarter the frequency of an external clock. External driving frequency will be less than 4 times as maximum internal clock. For external driving, no XTAL should be connected. An example of connection circuit is shown in Fig. 12.

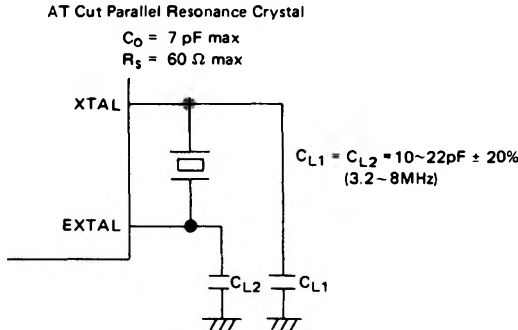


Figure 12 Crystal interface

STBY

This pin is used to place the MCU in the Stand-by mode. Setting to "Low" level, the internal condition is reset with inactive oscillation and fixed internal clock. In order to retain information in RAM during stand-by, write "0" into RAM enable bit (RAME). RAME is bit 6 of the RAM Control Register at address \$0014. This disables the RAM, so the contents of RAM is guaranteed. For details of the stand-by mode, see the STAND-BY section.

Reset ($\overline{\text{RES}}$)

This input is used to reset the MCU and start it from a power off condition. $\overline{\text{RES}}$ must be held "Low" for at least 20ms when power is on. To reset the MCU during system operation, it must be held "Low" at least 3 system clock cycles. From the third cycle on, all address buses become "High" with $\overline{\text{RES}}$ at "Low" level. Detecting "High" level, MPU does the following.

- (1) I/O Port 2 bits 2,1,0 are latched into bits PC2, PC1, PC0 of program control register.
- (2) The contents of the two Start Addresses, \$FFFE, \$FFFF are brought to the program counter, from which program starts (see Table 1).
- (3) The interrupt mask bit is set. In order to have the MPU recognize the maskable interrupts $\overline{\text{IRQ}}_1$ and $\overline{\text{IRQ}}_2$, clear it beforehand.

Enable (E)

With the internal oscillator in use, this supplies system clock for the rest of the system. Output is a single-phase, TTL compatible and 1/4 the crystal oscillation frequency. It will drive two LS TTL load and 40pF.

Non maskable Interrupt ($\overline{\text{NMI}}$)

When the input signal of this pin is recognized to fall, NMI sequence starts. The current instruction may be continued to the last if $\overline{\text{NMI}}$ signal is detected as well as the following $\overline{\text{IRQ}}_1$ interrupt. Interrupt mask bit in Condition Code Register has no effect on NMI. In response to NMI interrupt, the information of Program Counter, Index Register, Accumulators, and Condition Code Register are stored on the stack. On completion of this sequence, vectoring address \$FFFC and FFFD will occur to load the contents to the program counter and branch to a non maskable interrupt service routine.

Inputs $\overline{\text{IRQ}}_1$ and $\overline{\text{NMI}}$ are hardware interrupt lines sampled by internal clock. After the execution of instructions, start the interrupt routine in synchronization with E.

Interrupt Request ($\overline{\text{IRQ}}_1$)

This level sensitive input requests that an interrupt sequence be generated within the machine. The MPU will wait receiving the request until it completes the current instruction that being executed before it recognizes the request. At that time, if the interrupt mask bit in Condition Code Register is not set, MPU begins interrupt sequence; otherwise, interrupt request is neglected.

Once the sequence has started, the information of Program Counter, Index Register, Accumulator, Condition Code Register are stored on the stack. Then the MPU sets the interrupt bit so that no further maskable interrupts may occur.

Table 1 Interrupt Vectoring memory map

Highest Priority	Vector		Interrupt
	MSB	LSB	
	FFFE	FFFF	RES
	FFEE	FEFF	TRAP
	FFFC	FFFD	NMI
	FFFA	FFFB	Software Interrupt (SWI)
	FFB8	FFB9	$\overline{\text{IRQ}}_1$ (or $\overline{\text{IS3}}$)
	FFB6	FFB7	ICF (Timer Input Capture)
	FFF4	FFF5	OCF (Timer Output Compare)
	FFF2	FFF3	TOF (Timer Overflow)
Lowest Priority	FFF0	FFF1	SCI (RDRF + ORFE + TDRE)

At the end of the cycle, the MPU generates 16 bit vectoring addresses indicating memory addresses \$FFF8 and \$FFF9, and locates the contents in Program Counter to branch to an interrupt service routine.

The Internal Interrupt will generate signal ($\overline{\text{IRQ}}_2$) which is quite the same as $\overline{\text{IRQ}}_1$ except that it will use the vector address \$FFF0 to \$FFF7.

When $\overline{\text{IRQ}}_1$ and $\overline{\text{IRQ}}_2$ are generated at the same time, the former precede the latter. Interrupt Mask Bit in the condition code register, if being set, will keep the both interrupts off.

On occurrence of following Address Error or Op-code error, TRAP interrupt is invoked. This interrupt has priority next to RES. Independently of the Mask Bit condition, the MPU will start an interrupt sequence. The vector for this interrupt will be FFE4, FFE5.

The following pins are available only for Port 3 in single chip mode.

● **Input Strobe ($\overline{IS3}$) (SC_1)**

This signal controls $\overline{IS3}$ interrupt and the latch of Port 3. When detected the signal fall, the flag of Port 3 Control Status Register is set.

For respective bits of Port 3 Control Status Register, see the I/O PORT 3 CONTROL STATUS REGISTER section.

● **Output Strobe ($\overline{OS3}$) (SC_2)**

This signal is used to strobe to an external device, indicating effective data is on the I/O pins. The timing chart for Output Strobe are shown in figure 5.

The following pins are available for Expanded Modes.

● **Read/Write (R/\overline{W}) (SC_2)**

This TTL compatible output signal indicates peripheral and memory devices whether MCU is in Read ("High"), or in Write ("Low"). The normal stand-by state is Read ("High"). Its output will drive one TTL load and 90pF.

● **I/O Strobe (\overline{IOS}) (SC_1)**

In expanded non multiplexed mode 5 of operation, \overline{IOS} decodes internally A_9 to A_{15} as zero's and A_8 as a one. This allows external access up to 256 addresses from \$0100 to \$01FF in memory. The timing chart is shown in Figure 2.

● **Address Strobe (AS) (SC_1)**

In the expanded multiplexed mode, address strobe appears at this pin. It is used to latch the lower 8 bits addresses multiplexed with data at Port 3 and to control the 8-bit latch by address strobe as shown in Figure 18. Thereby, I/O Port 3 can become data bus during E pulse. The timing chart of this signal is shown in Figure 1.

■ **PORTS**

There are four I/O ports on HD6301V MCU (three 8-bit ports and one 5-bit port). 2 control pins are connected to one of the 8-bit port. Each port has an independent write-only data direction register to program individual I/O pins for input or output.*

When the bit of associated Data Direction Register is "1", I/O pin is programmed for output, if "0", then programmed for an input.

There are four ports.: Port 1, Port 2, Port 3, and Port 4. Addresses of each port and associated Data Direction Register are shown in Table 2.

* Only one exception is bit 1 of Port 2 which becomes either a data input or a timer output. It cannot be used as an output port.

Table 2 Port and Data Direction Register Addresses

Ports	Port Address	Data Direction Register Address
I/O Port 1	\$0002	\$0000
I/O Port 2	\$0003	\$0001
I/O Port 3	\$0006	\$0004
I/O Port 4	\$0007	\$0005

● **I/O Port 1**

This is an 8-bit port, each bit being defined individually as input or outputs by associated Data Direction Register. The 8-bit output buffers have three-state capability, maintaining in high impedance state when they are used for input. In order to

be read accurately, the voltage on the input lines must be more than 2.0V for logic "1" and less than 0.8V for logic "0".

These are TTL compatible. After the MCU has been reset, all I/O lines are configured as inputs in all modes except mode 1. In all modes other than expanded non multiplexed mode, mode 1, Port 1 is always parallel I/O. In mode 1, Port 1 will be output line for lower order address lines (A_0 to A_7).

● **I/O Port 2**

This port has five lines, whose I/O direction depends on its data direction register. The 5-bit output buffers have three-state capability, going high impedance state when used as inputs. In order to be read accurately, the voltage on the input lines must be more than 2.0V for logic "1" and less than 0.8V for logic "0". After the MCU has been reset, I/O lines are configured as inputs. These pins on Port 2 (pins 10, 9, 8 of the chip) are used to program the mode of operation during reset. The values of these three pins during reset are latched into the upper 3 bits (bit 7, 6 and 5), which is expanded in the MODE SELECTION section.

In all modes, Port 2 can be configured as I/O lines. This port also provides access to the Serial I/O and the Timer. However, note that bit 1 (P_{21}) is the only pin restricted to data input or Timer output.

● **I/O Port 3**

This is an 8-bit port which can be configured as I/O lines, a data bus, or an address bus multiplexed with data bus. Its function depends on hardware operation mode programmed by the user using 3 bits of Port 2 during Reset. Port 3 as a data bus is bi-directional. For an input from peripherals, regular TTL level must be supplied, that is greater than 2.0V for a logic "1" and less than 0.8V for a logic "0". This TTL compatible three-state buffer can drive one TTL load and 90pF. In the expanded Modes, data direction register will be inhibited after Reset and data flow will be dependent on the state of the R/\overline{W} line. Port 3 in each mode assumes the following characteristics.

Single Chip Mode (Mode 7): Parallel Inputs/Outputs as programmed by its corresponding Data Direction Register.

There are two control lines associated with this port in this mode, an input strobe ($\overline{IS3}$) and an output strobe ($\overline{OS3}$), both being used for handshaking. They are controlled by I/O Port 3 Control/Status Register. Additional 3 characteristics of Port 3 are summarized as follows:

- (1) Port 3 input data can be latched using $\overline{IS3}$ (SC_1) as a control signal.
- (2) $\overline{OS3}$ can be generated by MPU read or write to Port 3's data register.
- (3) IRQ_1 interrupt can be generated by an $\overline{IS3}$ negative edge.

Port 3 strobe and latch timing is shown in Figs. 5 and 6, respectively.

I/O Port 3 Control/Status Register							
7	6	5	4	3	2	1	0
$\overline{IS3}$	$\overline{IS3}$	X	$\overline{OS3}$	LATCH	X	X	X
FLAG	IRQ_1 ENABLE			ENABLE			
\$000F							

Bit 0 Not used.

Bit 1 Not used.

Bit 2 Not used.

Bit 3 LATCH ENABLE.

Bit 3 is used to control the input latch of Port 3. If the bit is set at "1", the input data on Port 3 is latched by the falling edge of $\overline{IS3}$. The latch is cleared by the MCU read to Port 3; it can now be latched again. Bit 3 is cleared by a reset.

Bit 4 OSS (Output Strobe Select)

This bit identifies the cause of output strobe generation: a write operation or read operation to I/O Port 3. When the bit is cleared, the strobe will be generated by a read operation to Port 3. When the bit is not cleared, the strobe will be generated by a write operation. Bit 4 is cleared by a reset.

Bit 5 Not used.

Bit 6 $\overline{IS3}$ ENABLE.

If the $\overline{IS3}$ flag (bit 7) is set with bit 6 set, an interrupt is enabled. Clearing the flag causes the interrupt to be disabled. The bit is cleared by a reset.

Bit 7 $\overline{IS3}$ FLAG.

Bit 7 is a read-only bit which is set by the falling edge of $\overline{IS3}$ (SC_1). It is cleared by a read of the Control/Status Register followed by a read/write of I/O Port 3. The bit is cleared by reset.

Expanded non multiplexed mode (mode 1,5)

In this mode, Port 3 becomes data bus. (D_0 to D_7)

Expanded Multiplexed Mode (mode 0, 4, 6)

Port 3 becomes both the data bus ($D_0 \sim D_7$) and lower bits of the address bus ($A_0 \sim A_7$). An address strobe output is true when the address is on the port.

● I/O Port 4

This is an 8-bit port that becomes either I/O or address outputs depending on the operation mode selected. In order to be read accurately, the voltage at the input lines must be greater than 2.0V for a logic "1", and less than 0.8V for a logic "0". For outputs, each line is TTL compatible and can drive one TTL load and 90pF. After reset, this port becomes inputs. To use these pins as addresses, they should be programmed as outputs.

In each mode, Port 4 assumes following characteristics.

Single Chip Mode (Mode 7): Parallel Inputs/Outputs as programmed by its associated data direction register.

Expanded Non Multiplexed Mode (Mode 5): In this mode, Port 4 becomes the lower address lines (A_0 to A_7) by writing "1"s on the data direction register.

When all of the eight bits are not required as addresses, the remaining lines can be used as I/O lines (Inputs only) starting with the MSB.

Expanded Non Multiplexed Mode (Mode 1): In this mode, Port 4 becomes output for upper order address lines (A_8 to A_{15}).

Expanded Multiplexed Mode (Mode 0, 4): In this mode, Port 4 becomes output for upper order address lines (A_8 to A_{15}) regardless of the value of data direction register. The relation between each mode and I/O Port 1 to 4 is summarized in Table 3.

■ MODE SELECTION

The operation mode after the reset must be determined by the user wiring the 10, 9, and 8 externally. These three pins are lower order bits; I/O 0, I/O 1, I/O 2 of Port 2. They are latched into the programmed control bits PC0, PC1, PC2 in I/O Port 2 register when reset goes "High", I/O Port 2 Register is shown below.

Port 2 DATA REGISTER

	7	6	5	4	3	2	1	0
\$0003	PC2	PC1	PC0	I/O 4	I/O 3	I/O 2	I/O 1	I/O 0

An example of external hardware used for Mode Selection is shown in Fig. 13. During reset, the HD14053B is available to separate the peripheral device from the MCU. It is necessary where the data conflict can occur between peripheral device and Mode generation circuit.

No mode can be changed through software because the bits 5, 6, and 7 of Port 2 are for read only. The mode selection of the HD6301V0 is shown in Table 4.

The HD6301V0 operates in three basic modes: (1) Single Chip Mode, (2) Expanded Multiplexed Mode (compatible with the HMCS6800 peripheral family), (3) Expanded Non Multiplexed Mode (compatible with HMCS6800 peripheral family)

● Single Chip Mode

In the Single Chip Mode, all ports will become I/O. This is shown in figure 15. In this mode, SC_1 , SC_2 pins are configured for control lines of Port 3 and can be used as input strobe ($\overline{IS3}$) and output strobe ($\overline{OS3}$) for handshaking data.

● Expanded Multiplexed Mode

In this mode, Port 4 is configured for I/O (inputs only) or address lines. The data bus and the lower order address bus are multiplexed in Port 3 and can be separated by an output called Address Strobe.

Port 2 is configured for 5 parallel I/O or Serial I/O, or Timer, or any combination thereof. Port 1 is configured for 8 parallel I/O. In this mode, HD6301V0 is expandable to 65k words (See Fig. 16).

● Expanded Non Multiplexed Mode

In this mode, the HD6301V0 can directly address HMCS6800 peripherals with no external logic. In mode 5, Port 3 becomes a data bus. Port 4 becomes A_0 to A_7 address bus or partial address bus and I/O (inputs only). Port 2 is configured for a parallel I/O, Serial I/O, Timer or any combination thereof.

Port 1 is configured as a parallel I/O only.

In this mode, HD6301V0 is expandable to 256 locations. In the application system enough with fewer addresses, idle pins of Port 4 can be used as I/O lines (inputs only) (See Fig. 17).

In mode 1, Port 3 becomes a data bus and Port 1 becomes A_0 to A_7 address bus, and Port 4 becomes A_8 to A_{15} address bus.

In this mode, the HD6301V0 is expandable to 65k words with no external logic.

● Lower Order Address Bus Latch

Because the data bus is multiplexed with the lower order address bus in Port 3 in the expanded multiplexed mode, address bits must be latched outside the board. It requires the 74LS373 Transparent octal D-type to latch the LSB. Latch connection of the HD6301V0 is shown in Figure 18.

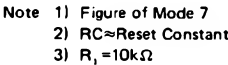


Figure 13 Recommended Circuit for Mode Selection

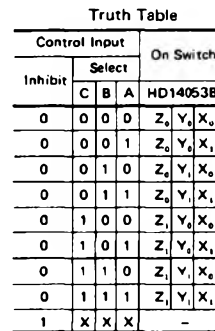


Figure 14 HD14053B Multiplexers/De-Multiplexers

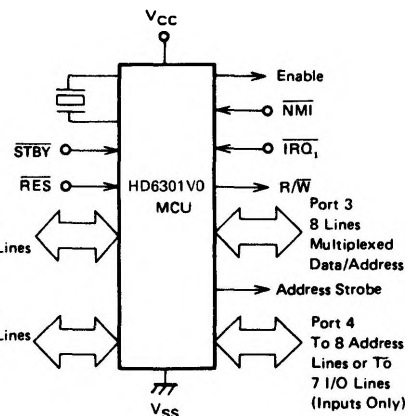


Figure 15 HD6301V0 MCU Single-Chip Mode

Figure 16 HD6301V0 MCU Expanded Multiplexed Mode

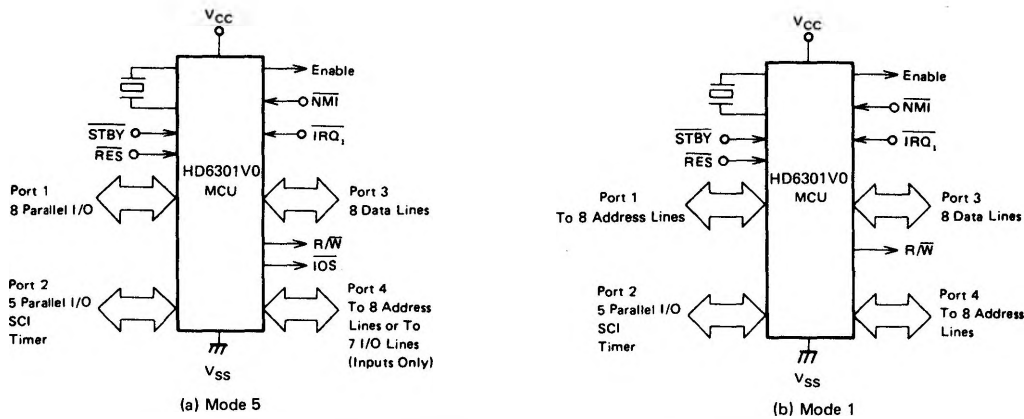


Figure 17 HD6301V0 MCU Expanded Non Multiplexed Mode

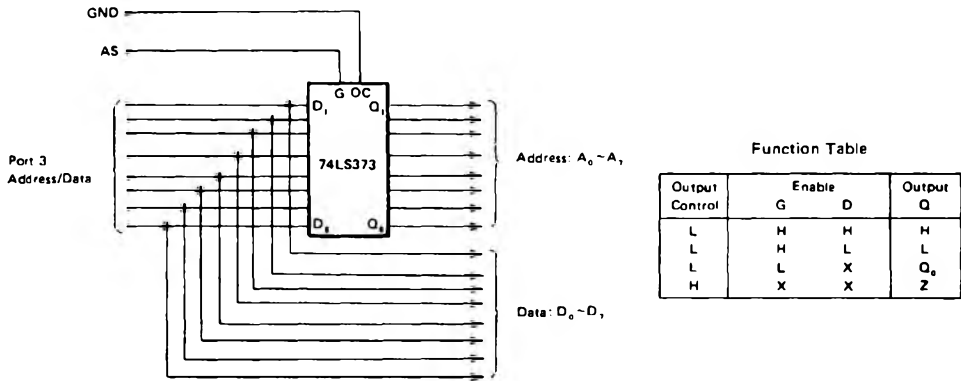


Figure 18 Latch Connection

• Mode and Port Summary MCU Signal Description

This section gives a description of the MCU signals for the various modes. SC₁ and SC₂ are signals which vary with the mode that the chip is in.

Table 3 Feature of each mode and lines

MODE		PORT 1 Eight Lines	PORT 2 Five Lines	PORT 3 Eight Lines	PORT 4 Eight Lines	SC ₁	SC ₂
SINGLE CHIP		I/O	I/O	I/O	I/O	IS3 (I)	OS3 (O)
EXPANDED MUX		I/O	I/O	ADDRESS BUS (A ₀ ~A ₇) DATA BUS (D ₀ ~D ₇)	ADDRESS BUS* (A ₈ ~A ₁₅)	AS(O)	R/W(O)
EXPANDED	Mode 5	I/O	I/O	DATA BUS (D ₀ ~D ₇)	ADDRESS BUS* (A ₀ ~A ₇)	IOS(O)	R/W(O)
NON-MUX	Mode 1	ADDRESS BUS (A ₀ ~A ₇)	I/O	DATA BUS (D ₀ ~D ₇)	ADDRESS BUS (A ₈ ~A ₁₅)	Not Used	R/W(O)

*These lines can be substituted for I/O (Input Only) starting with the MSB (except Mode 0, 4).

I	= Input	IS3	= Input Strobe	SC	= Strobe Control
O	= Output	OS3	= Output Strobe	AS	= Address Strobe
R/W	= Read/Write	IOS	= I/O Select		

Table 4 Mode Selection Summary

Mode	P ₃ (PC2)	P ₂ (PC1)	P ₁ (PC0)	ROM	RAM	Interrupt Vectors	Bus Mode	Operating Mode
7	H	H	H	I	I	I	I	Single Chip
6	H	H	L	I	I	I	MUX(4)	Multiplexed/Partial Decode
5	H	L	H	I	I	I	NMUX(4)	Non-Multiplexed/Partial Decode
4	H	L	L	E(2)	I(1)	E	MUX	Multiplexed/RAM
3	L	H	H	—	—	—	—	Not Used
2	L	H	L	—	—	—	—	Not Used
1	L	L	H	E(2)	I	I	NMUX	Non-Multiplexed
0	L	L	L	I	I	I(3)	MUX	Multiplexed Test

LEGEND :

I — Internal
E — External
MUX — Multiplexed
NMUX — Non-Multiplexed
L — Logic "0"
H — Logic "1"

(NOTES)

- 1) Internal RAM is addressed at \$0080.
- 2) Internal ROM is disabled.
- 3) Reset vector is external for 3 or 4 cycles after RES goes "high".
- 4) Idle lines of Port 4 address outputs can be assigned to Input Port.

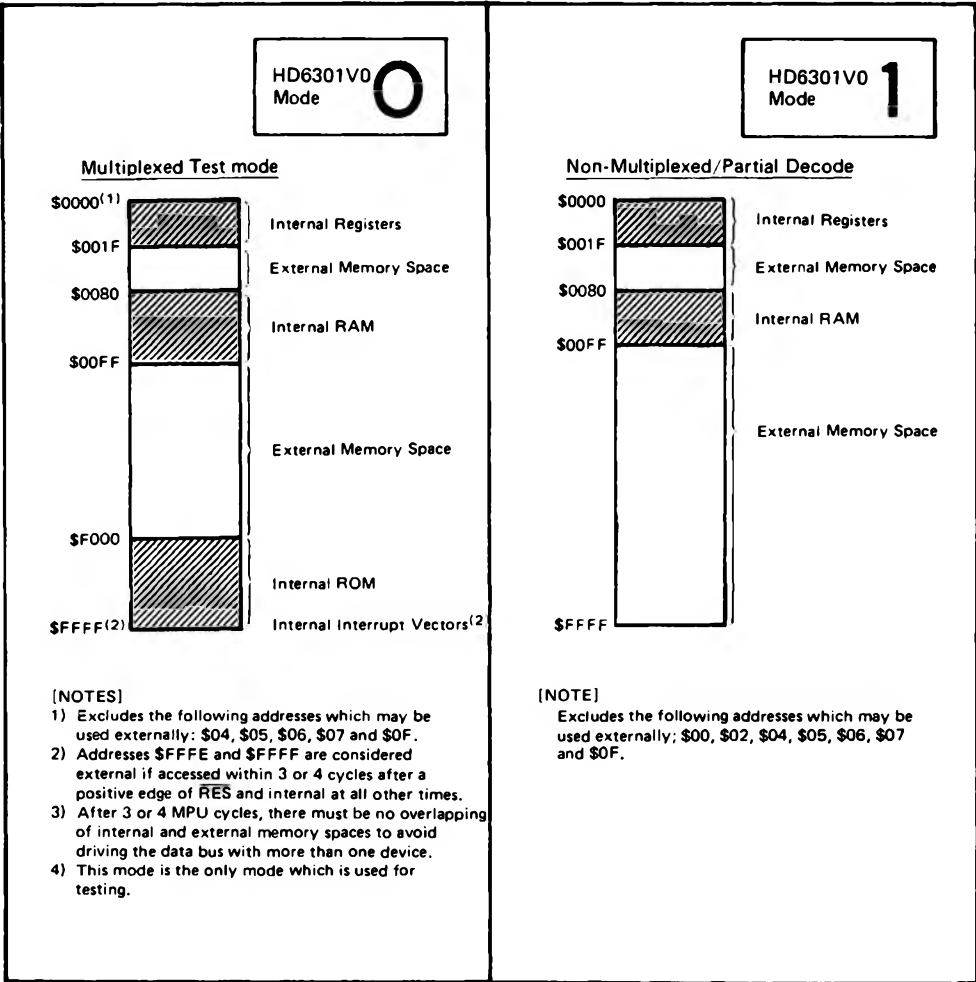
■ Memory Map

The MCU can provide up to 65k byte address space depending on the operating mode. Fig. 19 shows a memory map for each operating mode. The first 32 locations of each map are for the MCU's internal register only, as shown in Table 5.

Table 5 Internal Register Area

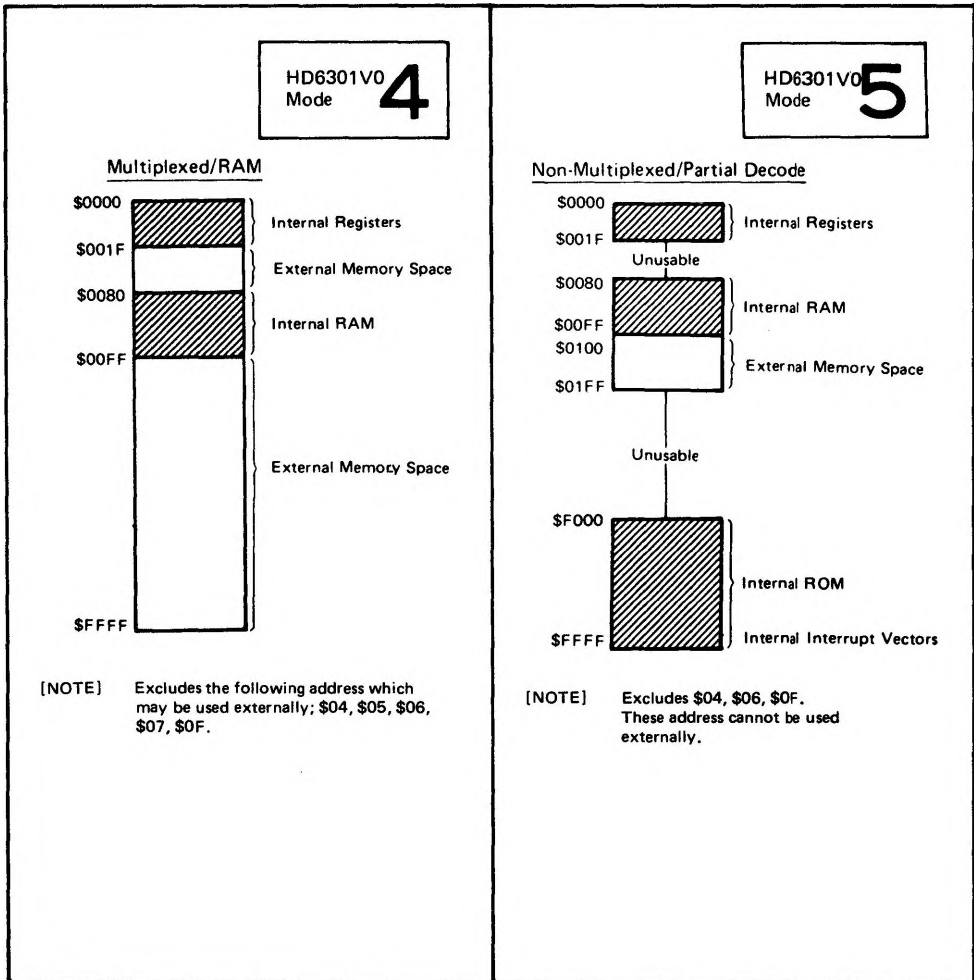
Register	Address
Port 1 Data Direction Register ****	00*
Port 2 Data Direction Register ****	01
Port 1 Data Register	02*
Port 2 Data Register	03
Port 3 Data Direction Register ****	04**
Port 4 Data Direction Register ****	05***
Port 3 Data Register	06**
Port 4 Data Register	07***
Timer Control and Status Register	08
Counter (High Byte)	09
Counter (Low Byte)	0A
Output Compare Register (High Byte)	0B
Output Compare Register (Low Byte)	0C
Input Capture Register (High Byte)	0D
Input Capture Register (Low Byte)	0E
Port 3 Control and Status Register	0F**
Rate and Mode Control Register	10
Transmit/Receive Control and Status Register	11
Receive Data Register	12
Transmit Data Register	13
RAM Control Register	14
Reserved	15-1F

- * External address in Mode 1
- ** External address in modes 0, 1, 4, 6 ; cannot be accessed in Mode 5
- *** External address in Modes 0, 1, 4
- **** 1 = Output, 0 = Input



(to be continued)

Figure 19 HD6301V0 Memory Maps



(to be continued)

Figure 19 HD6301V0 Memory Maps

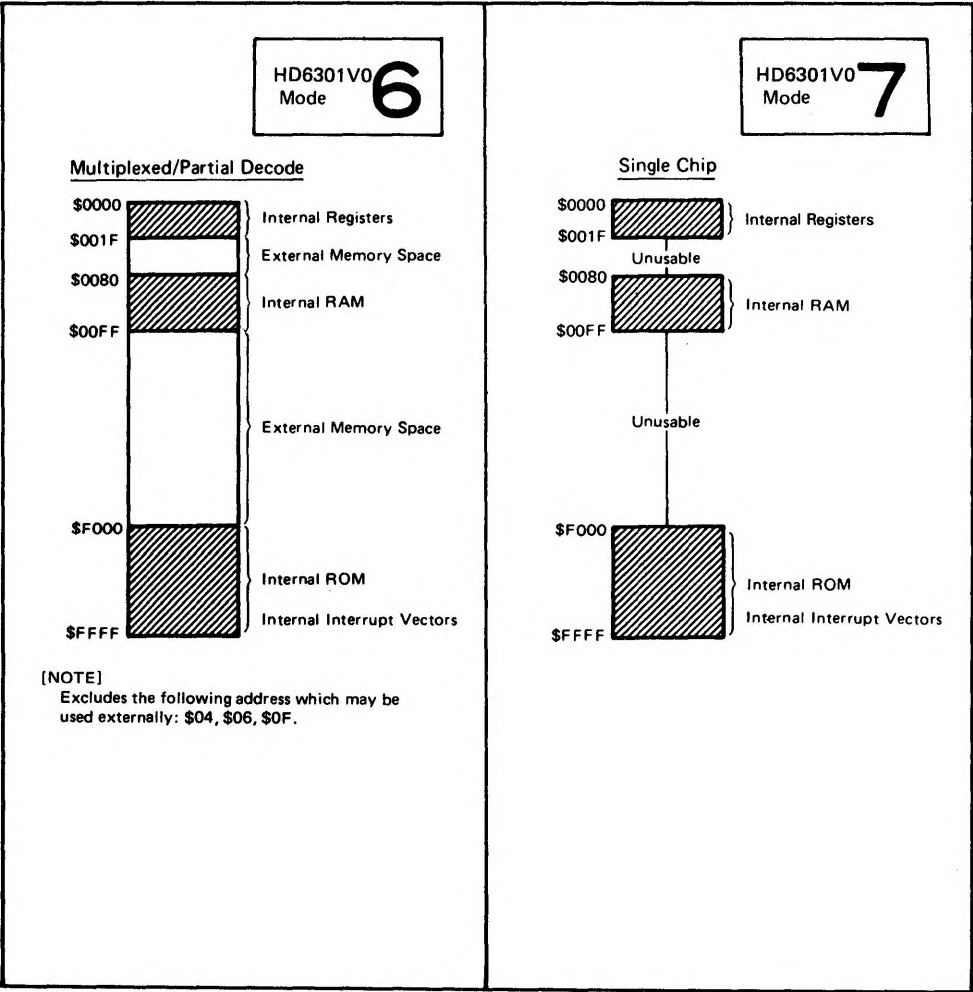


Figure 19 HD6301V0 Memory Maps

PROGRAMMABLE TIMER

The HD6301V0 contains 16-bit programmable timer and used to make measurement of input waveform. In addition independently it can generate an output waveform by itself. For both input and output waveform, the pulse width may vary from a few microseconds to many seconds.

The timer hardware consists of

- an 8-bit control and status register
- a 16-bit free running counter
- a 16-bit output compare register, and
- a 16-bit input capture register

A block diagram of the timer is shown in Figure 20.

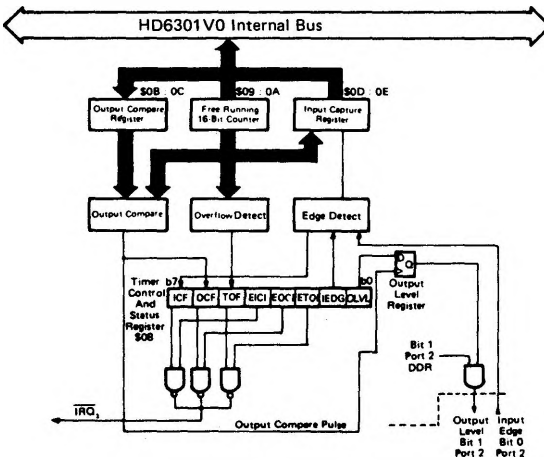


Figure 20 Programmable Timer Block Diagram

Free Running Counter (\$0009:\$000A)

The key element in the programmable timer is a 16-bit free running counter, that is driven by an E (Enable) clock to increment its values. The counter value will be read out by the MPU software at any time desired with no effects on the counter. Reset will clear the counter.

When the MPU writes arbitrary data to the MSB of \$09, then value of \$FFF8 is being pre set to the count (\$09, \$0A) independently of the write data value. When the MPU writes arbitrary data to the LSB (\$0A), the data is set to the "Low", on the other hand, the data preceedingly written in "High" byte is set to "High".

The counter value written to the counter using the double store instruction is shown in Figure 21.

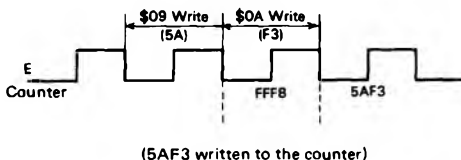


Figure 21 Counter Write Timing

* To write to the counter can disturb serial operations, so it should be inhibited during using the SCI.

Output Compare Register (\$000B:\$000C)

This is a 16-bit read/write register which is used to control an output waveform. The contents of this register are constantly being compared with current value of the free running counter.

When the contents match with the value of the free running counter, a flag (OCF) in the timer control/status register (TCSR) is set and the current value of an output level Bit (OLVL) in the TCSR is transferred to Port 2 bit 1. When bit 1 of the Port 2 data direction register is "1" (output), the OLVL value will appear on the bit 1 of Port 2. Then, the value of Output Compare Register and Output level bit should be changed to control an output level again on the next compare values.

The output compare register is set to \$FFFF during reset. The compare function is inhibited for one cycle immediately after writing of the output compare register to the upper bytes, or, a writing of the Counter to the upper bytes. This is because for one thing, the operation makes sure to set the values of 16 bits in the register before comparing, and for another, the counter is set to FFF8 in the cycle following writing to "High" of the counter.*

* For the data writing on Compare Register, 2-byte transfer instruction such as STX is available.

Input Capture Register (\$000D:\$000E)

The input capture register is a 16-bit read-only register used to hold the current value of free running counter obtained when the proper transition of an external input signal occurs.

The input transition change required to trigger the counter transfer is controlled by the input Edge bit (IEDG).

To allow the external input signal to gate in the edge detect unit, the bit of the Data Direction Register corresponding to bit 0 of Port 2 must have been cleared (to zero).

To insure input capture in all cases, the width of an input pulse requires at least 2 Enable cycles.

Timer Control/Status Register (TCSR) (\$0008)

This is an 8-bit register. All 8 bits are readable and the lower 5 bits may be written. The upper 3 bits are read-only, indicating the timer status information below.

- (1) A proper transition has taken place on the input pin with a subsequent transfer of the current counter value to the input capture register (ICF).
- (2) A match has been found between the value in the free running counter and the output compare register (OCF).
- (3) When counting up to \$0000 (TOF).

Each flag may contain an individual enable bit in TCSR where controls whether or not an interrupt request may be output to internal interrupt signal (IRQ₂). If the 1-bit in Condition Code Register has been cleared, a priority vectored address occurs corresponding to each flag being set. A description of each bit is as follows.

Timer Control / Status Register

7	6	5	4	3	2	1	0	
ICF	OCF	TOF	EICI	EOCI	ETOI	IEDG	OLVL	\$0008

Bit 0 OLVL (Output Level): When a match is found in the value between the counter and the output compare register, this bit is transferred to the Port 2 bit 1. If the DDR corresponding to Port 2 bit 1 is set "1", the value will appear on the output pin of Port 2 bit 1.

Bit 1 IEDG (Input Edge); This bit control which transition of an input of Port 2 bit 0 will trigger the data transfer from the counter to the input capture register. The DDR corresponding to Port 2 bit 0 must be clear in advance of using this function. When IEDG = 0, trigger takes place on a negative edge ("High"-to-"Low" transition). When IEDG = 1, trigger takes place on a leading edge ("Low"-to-"High" transition).

Bit 2 ETOI (Enable Timer Overflow Interrupt); When set, this bit enables TOF interrupt to generate the interrupt request ($\overline{IRQ_2}$) but when clear, the interrupt is inhibited.

Bit 3 EOCI (Enable Output Compare Interrupt); When set, this bit enables OCF interrupt to generate the interrupt request ($\overline{IRQ_2}$), when clear, the interrupt is inhibited.

Bit 4 EICI (Enable Input Capture Interrupt); When set, this bit enables ICF interrupt to generate the interrupt request ($\overline{IRQ_2}$) but when clear, the interrupt is inhibited.

Bit 5 TOF (Timer Over Flow Flag); This read-only bit is set when the counter value is \$0000. It is cleared by MPU read of TCSR (with TOF set) following an MPU read of the counter (\$0009).

Bit 6 OCF (Output Compare Flag); This read-only bit is set when a match is found in the value between the output compare register and the counter. It is cleared by a read of TCSR (with OCF set) following an MCU write to the output compare register (\$000B or \$000C).

Bit 7 ICF (Input Capture Flag); The read-only bit is set by a proper transition on the input, and is cleared by a read of TCSR (with ICF set) followed by an MPU read of Input Capture Register (\$000D).

Reset will clear each bit of Timer Control and Status Register.

SERIAL COMMUNICATION INTERFACE

The HD6301V0 contains a full-duplex asynchronous Serial Communication Interface (SCI). SCI may select the several kinds of the data rate and comprises a transmitter and a receiver which operate independently on each other but with the same data format at the same data rate. Both of transmitter and receiver communicate with the MPU via the data bus and with the outside world, through Port 2 bit 2, 3 and 4. Description of hardware, software, register is as follows.

Wake-Up Feature

In typical multiprocessor applications the software protocol will usually have the designated address at the initial byte of the message. The purpose of Wake-Up feature is to have the non-selected MPU neglect the remainder of the message. Thus the non-selected MPU can inhibit the all further interrupt process until the next message begins.

Wake-Up feature is triggered by a ten consecutive "1"s which indicates an idle transmit line. Therefore software protocol needs an idle period between the messages.

With this hardware feature, the non-selected MPU be re-enabled (or "wakes-up") for the appearing next message.

Programmable Option

The HD6301V0 has the following optional features provided for its Serial I/O. They are all programmable.

- data format ; standard mark/space (NRZ)
- Clock Source ; external or internal
- baud rate ; one of 4 rates per given MPU E clock frequency or 1/8 of external clock
- wake-up feature ; Enabled or disabled
- Interrupt requests ; enabled or masked individually for transmitter and receive data registers
- Clock Output ; internal clock enabled or disabled to Port 2 bit 2
- Port 2 (bits 3, 4) ; dedicated or not dedicated to serial I/O individually for receiver and transmitter

Serial Communication Hardware

The serial communications hardware is controlled by 4 registers as shown in Figure 22. The registers include:

- an 8-bit control/status register
- a 4-bit rate/mode control register (write-only)
- an 8-bit read-only receive data register
- an 8-bit write-only transmit data register

Besides these 4 registers, Serial I/O utilizes Port 2 bit 3 (input) and bit 4 (output). Port 2 bit 2 can be used when an option is selected for the internal-clock-out or the external-clock-in.

Transmit/Receive Control Status Register (TRCSR)

TRCS Register consists of 8 bits which all may be read while only bits 0 to 4 may be written. The register is initialized to \$20 on RES. The bits of the TRCS register are defined as follows.

Transmit / Receiver Control Status Register

7	6	5	4	3	2	1	0	ADDR:
RDRF	ORFE	TDRE	RIE	RE	TIE	TE	WU	\$0011

Bit 0 WU (Wake Up); Set by software and clear by hardware on receipt of ten consecutive "1"s. It should be noted that RE flag has already set in advance of WU flag's set.

Bit 1 TE (Transmit Enable); Set to produce preamble of ten consecutive "1"s and to enable the data of transmitter to output subsequently to the Port 2 bit 4 independently of its corresponding DDR value. When clear, serial I/O affects nothing on Port 2 bit 4.

Bit 2 TIE (Transmit Interrupt Enable); When this bit is set with TDRE (bit 5) set, it will permit an $\overline{IRQ_2}$ interrupt. When clear, TDRE interrupt is masked.

Bit 3 RE (Receive Enable); When set, gates Port 2 bit 3 to input of receiver regardless of DDR value for this bit. When clear, the serial I/O affects nothing on Port 2 bit 3.

Bit 4 RIE (Receive Interrupt Enable); When this bit is set with bit 7 (RDRF) or a bit 6 (ORFE) set, it will permit an $\overline{IRQ_2}$. When clear, $\overline{IRQ_2}$ interrupt is masked.

Bit 5 TDRE (Transmit Data Register Empty); When the data transfer is made from the Transmit Data Register to Output Shift Register, it is set by hardware. The bit is cleared by reading the status register and followed by writing the next new data into the Transmit Data Register. TDRE is initialized to 1 by RES.

Bit 6 ORFE (Over Run Framing Error); When overrun or

framing error occurs (receive only), it is set by hardware. Over Run Error occurs if the attempt is made to transfer the new byte to the receive data register with the RDRF set. Framing Error occurs when the bit counters are not synchronized with the boundary of the byte in the bit stream. The bit is cleared by reading the status register and

followed by reading the receive data register, or by RES.

Bit 7 RDRF (Receive Data Register Full); It is set by hardware when the data transfer is made from the receive shift register to the receive data register. It is cleared by reading the status register and followed by reading the receive data register, or by RES.

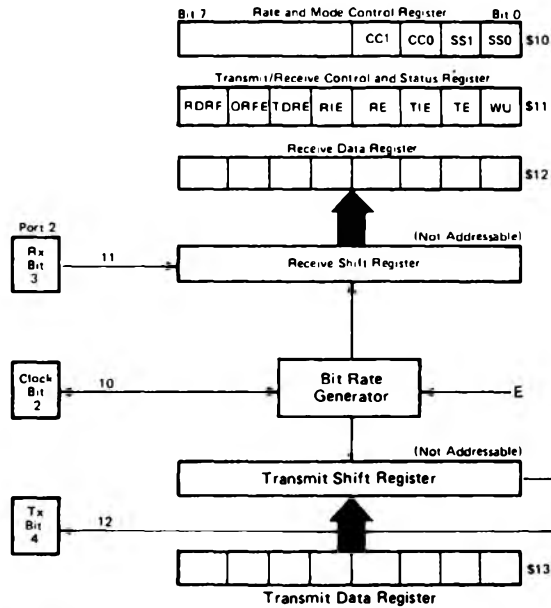


Figure 22 Serial I/O Register

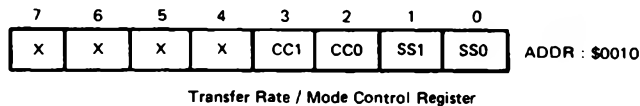


Table 6 SCI Bit Times and Transfer Rates

SS1 : SS0	XTAL	2.4576 MHz	4.0 MHz	4.9152MHz
	E	614.4 kHz	1.0 MHz	1.2288MHz
0 0	E ÷ 16	26 μs/38,400 Baud	16 μs/62,500 Baud	13 μs/76,800Baud
0 1	E ÷ 128	208μs/4,800 Baud	128 μs/7812.5 Baud	104.2μs/ 9,600Baud
1 0	E ÷ 1024	1.67ms/600 Baud	1.024ms/976.6 Baud	833.3μs/ 1,200Baud
1 1	E ÷ 4096	6.67ms/150 Baud	4.096ms/244.1 Baud	3.333ms/ 300Baud

Table 7 SCI Format and Clock Source Control

CC1, CC0	Format	Clock Source	Port 2 Bit 2	Port 2 Bit 3	Port 2 Bit 4 -
00	—	—	—	—	—
01	NRZ	Internal	Not Used	••	••
10	NRZ	Internal	Output*	••	••
11	NRZ	External	Input	••	••

- * Clock output is available regardless of values for bits RE and TE.
- Bit 3 is used for serial input if RE = "1" in TRCS.
Bit 4 is used for serial output if TE = "1" in TRCS.

● **Transfer rate/Mode Control Register (RMCR)**

The register controls the following serial I/O variables:

- Bauds rate • data format • clock source
- Port 2 bit 2 feature

It is 4-bit write-only register, cleared by \overline{RES} . The 4 bits are considered as a pair of 2-bit fields. The lower 2 bits control the bit rate of internal clock while the upper 2 bits control the format and the clock select logic.

Bit 0 SS0 }
Bit 1 SS1 } Speed Select

These bits select the Baud rate for the internal clock. The rates selectable are function of E clock frequency within the MPU. Table 6 lists the available Band Rates.

Bit 2 CC0 }
Bit 3 CC1 } Clock Control/Format Select

They control the data format and the clock select logic. Table 7 defines the bit field.

● **Internally Generated Clock**

If the user wish to employ externaly a internal clock for the serial I/O, the following requirements should be noted.

- The values of RE and TE have no effect.
- CC1, CC0 must be set to "10".
- The maximum clock rate will be E/16.
- The clock is once the bit rate.

● **Externally Generated Clock**

If the user wish to supply an external clock for the Serial I/O, the following requirements should be noted.

- The CC1, CC0, field in the Rate and Mode Control Register must be set to "11" (See Table 7).
- The external clock must be set to 8 times the desired baud rate.
- The maximum external clock frequency is the same as E clock.

● **Serial Operations**

The serial I/O hardware must be initialized by the HD6301V0 software prior to operation. The sequence will be normally as follows.

- Writing the desired operation control bits to the Rate and Mode Control Register.
- Writing the desired operation control bits to the TRCS register.

If using Port 2 bit 3, 4 for serial I/O exclusively, TE, RE bits may be preserved set. When TE, RE bit cleared during SCI operation, and subsequently set again, it should be noted that the setting of TE, RE must refrain for at least one bit time of the current baud rate. If set within one bit time, there may be the case where the initializing of internal function for transmit and receive does not take place.

● **Transmit Operation**

Data transmission is enabled by the TE bit in the TRCS register. When set, gates the output of the serial transmit shift register to Port 2 bit 4 which is unconditionally configured as an output irrespectively of corresponding DDR value.

Following \overline{RES} the user should configure both the RMC register and the TRCS register for desired operation. Setting the TE bit during this procedure causes a transmission of ten-bit preamble of "1"s. Following the preamble, internal synchronization is established and the transmitter section is ready to operate. Then either of the following states exists.

- (1) If the transmit data register is empty (TDRE = 1), the

consecutive "1"s are transmitted indicating an idle lines.

- (2) If the data has been loaded into the Transmit Data Register (TDRE = 0), it is transferred to the output shift register and data transmission begins.

During the data transfer, the 0 start bit is first transferred. Next the 8-bit data (beginning at bit0) and the stop bit. When the transmit data register has been empty, the hardware sets the TDRE flag bit: If the MCU fails to respond to the flag within the proper time, TDRE is preserved set and then a 1 will be sent (instead of a 0 at start bit time) and more 1s will be set successively until the data is supplied to the data register. While the TDRE remains a "1", no "0" will be sent.

● **Receive Operation**

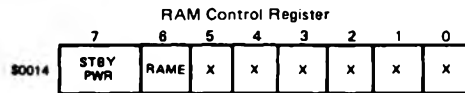
The receive operation is enabled by the RE bit, gating the serial input through Port 2 bit 3. The receive section operation is conditioned by the contents of the TRCS and RMC register. In the normal non-biphase mode, the received bit stream is synchronized by the first "0" (space). During 10-bit time, the approximate center is strobed. If the tenth bit is not "1" (stop bit), the system assumes a framing error and the ORFE is set.

If the tenth bit is "1", the data is transferred to the receive data register, with the interrupt flag set. If the tenth bit of the next data is received, however, still RDRF is preserved set, then ORFE is set indicating that an overrun error has occurred.

After the MCU read of the status register as a response to RDRF flag or ORFE flag, following the MCU read of the receive data register, RDRF or ORFE will be cleared.

■ **RAM CONTROL REGISTER**

The register assigned to the address \$0014 gives a status information about standby RAM.



Bit 0 Not used.

Bit 1 Not used.

Bit 2 Not used.

Bit 3 Not used.

Bit 4 Not used.

Bit 5 Not used.

Bit 6 RAM Enable.

Using this control bit, the user can disable the RAM. When the MPU is reset, "1" is set in the RAM Enable bit thus enabling the standby RAM. With the program control, it is capable of writing "1" or "0". With the disabled RAM (logic "0"), the RAM address becomes external address and the MPU may read the data from the outside memory.

Bit 7 Standby Bit

This bit is cleared when the V_{CC} voltage is removed. This bit is a read/write status flag that user can read. If this bit is preserved set, indicating that V_{CC} voltage is applied and the data in the RAM is valid.

■ **GENERAL DESCRIPTION OF INSTRUCTION SET**

The HD6301V0 has an upward object code compatible with the HD6801 to utilize all instruction sets of the HMCS6800. The execution time of the key instruction is reduced to increase the system through-put. In addition, the bit operation instruction, the change instruction of the index and the accumulator, the sleep instruction are added. This section describes:

- MCU programming model (See Fig. 23)
- Addressing modes
- Accumulator and memory manipulation instructions (See Table 8)
- New instructions
- Index register and stack manipulation instructions (See Table 9)
- Jump and branch instructions (See Table 10)
- Condition code register manipulation instructions (See Table 11)
- Op-code map (See Table 12)

• MCU Programming Model

The programming model for the HD6301V0 is shown in Figure 23. The double accumulator is physically the same as the accumulator A concatenated with the accumulator B, so that the contents of A and B is changed with executing operation of an accumulator D.

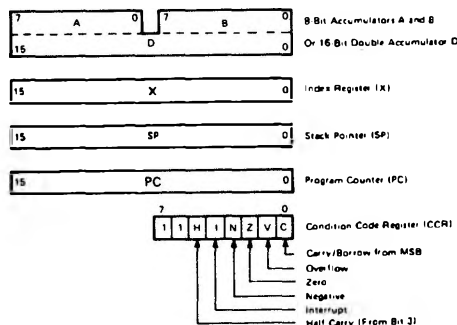


Figure 23 MCU Programming Model

• MCU Addressing Modes

The HD6301V0 has seven address modes which depend on both of the instruction type and the code. The address mode for every instruction is shown along with execution time given in terms of machine cycles (Table 8 to 12). When the clock frequency is 4 MHz, the machine cycle will be microseconds.

Accumulator (ACCX) Addressing

Only the accumulator (A or B) is addressed. Either accumulator A or B is specified by one-byte instructions.

Immediate Addressing

In this mode, the operand is stored in the second byte of the instruction except that the operand in LDS and LDX, etc are stored in the second and the third byte. These are two or three-byte instructions.

Direct Addressing

In this mode, the second byte of instruction indicates the address where the operand is stored. Direct addressing allows the user to directly address the lowest 256 Bytes in the machine ie; locations zero through 255. Enhanced execution times are achieved by storing data in these locations. For system configuration, it is recommended that these locations should be RAM and be utilized preferably for user's data realm. These are two-byte instructions except the AIM, OIM, EIM and TIM each have three.

Extended Addressing

In this mode, the second byte indicates the upper 8 bit addresses where the operand is stored, while the third byte indicates the lower 8 bits. This is an absolute address in

memory. These are three-byte instructions.

Indexed Addressing

In this mode, the contents of the second byte is added to the lower 8 bits in the Index Register. For each of AIM, OIM, EIM and TIM instructions, the contents of the third byte are added to the lower 8 bits in the Index Register. In addition, this carry is added to the upper 8 bits in the Index Register. The result is used for addressing memory. Because the modified address is held in the Temporary Address Register, there is no change to the Index Register. These are two-byte instructions but AIM, OIM, EIM, TIM have three.

Implied Addressing

In this mode, the instruction itself gives the address; stack pointer, index register, etc. These are 1-byte instructions.

Relative Addressing

In this mode, the contents of the second byte is added to the lower 8 bits in the program counter. The resulting carry or borrow is added to the upper 8 bits. This helps the user to address the data within a range of -126 to +129 bytes of the current execution instruction. These are two-byte instructions.

Table 8 Accumulator, Memory Manipulation Instructions

Operations	Mnemonic	Addressing Modes												Boolean/ Arithmetic Operation	Condition Code Register								
		IMMED			DIRECT			INDEX			EXTEND				IMPLIED			Register					
		OP	~	#	OP	~	#	OP	~	#	OP	~	#		OP	~	#	H	I	N	Z	V	C
Add	ADDA	8B	2	2	9B	3	2	A8	4	2	BB	4	3										
	ADDB	CB	2	2	DB	3	2	EB	4	2	FB	4	3										
Add Double	ADDD	C3	3	3	D3	4	2	E3	5	2	F3	5	3										
Add Accumulators	ABA													1B	1	1							
Add With Carry	ADCA	89	2	2	99	3	2	A9	4	2	B9	4	3										
	ADCB	C9	2	2	D9	3	2	E9	4	2	F9	4	3										
AND	ANDA	84	2	2	94	3	2	A4	4	2	B4	4	3										
	ANDB	C4	2	2	D4	3	2	E4	4	2	F4	4	3										
Bit Test	BIT A	85	2	2	95	3	2	A5	4	2	B5	4	3										
	BIT B	C5	2	2	D5	3	2	E5	4	2	F5	4	3										
Clear	CLR							6F	5	2	7F	5	3										
	CLRA													4F	1	1							
	CLRB													5F	1	1							
Compare	CMPA	81	2	2	91	3	2	A1	4	2	B1	4	3										
	CMPB	C1	2	2	D1	3	2	E1	4	2	F1	4	3										
Compare Accumulators	CBA													11	1	1							
Complement, 1's	COM							63	6	2	73	6	3										
	COMA													43	1	1							
	COMB													53	1	1							
Complement, 2's (Negate)	NEG							60	6	2	70	6	3										
	NEGA													40	1	1							
	NEGB													50	1	1							
Decimal Adjust, A	DAA													19	1	1							
Decrement	DEC							6A	6	2	7A	6	3										
	DECA													4A	1	1							
	DECB													5A	1	1							
Exclusive OR	EORA	88	2	2	98	3	2	A8	4	2	B8	4	3										
	EORB	C8	2	2	D8	3	2	E8	4	2	F8	4	3										
Increment	INC							6C	6	2	7C	6	3										
	INCA													4C	1	1							
	INCB													5C	1	1							
Load Accumulator	LDAA	86	2	2	96	3	2	A6	4	2	B6	4	3										
	LDAB	C6	2	2	D6	3	2	E6	4	2	F6	4	3										
Load Double Accumulator	LDD	CC	3	3	DC	4	2	EC	5	2	FC	5	3										
Multiply Unsigned	MUL													3D	7	1							
OR, Inclusive	ORAA	8A	2	2	9A	3	2	AA	4	2	BA	4	3										
	ORAB	CA	2	2	DA	3	2	EA	4	2	FA	4	3										
Push Data	PSHA													36	4	1							
	PSHB													37	4	1							
Pull Data	PULA													32	3	1							
	PULB													33	3	1							
Rotate Left	ROL							69	6	2	79	6	3										
	ROLA													49	1	1							
	ROLB													59	1	1							
Rotate Right	ROR							66	6	2	76	6	3										
	RORA													46	1	1							
	RORB													56	1	1							

Note) Condition Code Register will be explained in Note of Table 11.

(to be continued)

Table 8 Accumulator, Memory Manipulation Instructions

Operations	Mnemonic	Addressing Modes												Boolean/ Arithmetic Operation	Condition Code Register							
		IMMED			DIRECT			INDEX			EXTEND				IMPLIED			5	4	3	2	1
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#	H	I	N	Z	V	C
Shift Left Arithmetic	ASL							68	6	2	78	6	3									

Note) Condition Code Register will be explained in Note of Table 11.

• New Instructions

In addition to the HD6801 Instruction Set, the HD6301V0 has the following new instructions:

AIM----(M) · (IMM) → (M)

Evaluates the AND of the immediate data and the memory, places the result in the memory.

OIM----(M) + (IMM) → (M)

Evaluates the OR of the immediate data and the memory, places the result in the memory.

EIM----(M) ⊕ (IMM) → (M)

Evaluates the EOR of the immediate data and the contents of memory, places the result in memory.

TIM----(M) · (IMM)

Evaluates the AND of the immediate data and the memory, changes the flag of associated condition code register

Each instruction has three bytes; the first is op-code, the second is immediate data, the third is address modifier.

XGDX---(ACCD) ↔ (IX)

Exchanges the contents of accumulator and the index register.

SLP----The MPU is brought to the sleep mode. For sleep mode, see the "sleep mode" section.

Table 9 Index Register, Stack Manipulation Instructions

Pointer Operations	Mnemonic	Addressing Modes										Boolean/ Arithmetic Operation	Condition Code Register					
		IMMED		DIRECT		INDEX		EXTEND		IMPLIED			5	4	3	2	1	0
		OP	~ #	OP	~ #	OP	~ #	OP	~ #	OP	~ #		H	I	N	Z	V	C
Compare Index Reg	CPX	8C	3 3	9C	4 2	AC	5 2	BC	5 3			X ← M ← M + 1	•	•	•	•	•	•
Decrement Index Reg	DEX									09	1 1	X ← X - 1	•	•	•	•	•	•
Decrement Stack Ptr	DES									34	1 1	SP ← SP - 1	•	•	•	•	•	•
Increment Index Reg	INX									08	1 1	X ← X + 1	•	•	•	•	•	•
Increment Stack Ptr	INS									31	1 1	SP ← SP + 1	•	•	•	•	•	•
Load Index Reg	LDX	CE	3 3	DE	4 2	EE	5 2	FE	5 3			M → X _H , (M + 1) → X _L	•	•	⑦	•	•	•
Load Stack Ptr	LDS	8E	3 3	9E	4 2	AE	5 2	BE	5 3			M → SP _H , (M + 1) → SP _L	•	•	⑦	•	•	•
Store Index Reg	STX			DF	4 2	EF	5 2	FF	5 3			X _H → M, X _L → (M + 1)	•	•	⑦	•	•	•
Store Stack Ptr	STS			9F	4 2	AF	5 2	BF	5 3			SP _H → M, SP _L → (M + 1)	•	•	⑦	•	•	•
Index Reg → Stack Ptr	TXS									35	1 1	X ← SP	•	•	•	•	•	•
Stack Ptr → Index Reg	TSX									30	1 1	SP ← X	•	•	•	•	•	•
Add	ABX									3A	1 1	B ← X + X	•	•	•	•	•	•
Push Data	PSHX									3C	5 1	X _L → M _{sp} , SP ← SP	•	•	•	•	•	•
												X _H → M _{sp} , SP ← SP	•	•	•	•	•	•
Pull Data	PULX									38	4 1	SP ← SP + 1, M _{sp} → X _H	•	•	•	•	•	•
												SP ← SP + 1, M _{sp} → X _L	•	•	•	•	•	•
Exchange	XGDX									18	2 1	ACCD ← IX	•	•	•	•	•	•

Note) Condition Code Register will be explained in Note of Table 11.

Table 10 Jump, Branch Instruction

Operations	Mnemonic	Addressing Modes										Branch Test	Condition Code Register										
		RELATIVE		DIRECT		INDEX		EXTEND		IMPLIED			5	4	3	2	1	0					
		OP	~ #	OP	~ #	OP	~ #	OP	~ #	OP	~ #		H	I	N	Z	V	C					
Branch Always	BRA	20	3 2									None	•	•	•	•	•	•					
Branch Never	BRN	21	3 2									None	•	•	•	•	•	•					
Branch If Carry Clear	BCC	24	3 2									C = 0	•	•	•	•	•	•					
Branch If Carry Set	BCS	25	3 2									C = 1	•	•	•	•	•	•					
Branch If = Zero	BEQ	27	3 2									Z = 1	•	•	•	•	•	•					
Branch If > Zero	BGE	2C	3 2									$N \oplus V = 0$	•	•	•	•	•	•					
Branch If > Zero	BGT	2E	3 2									$Z + (N \oplus V) = 0$	•	•	•	•	•	•					
Branch If Higher	BHI	22	3 2									$C + Z = 0$	•	•	•	•	•	•					
Branch If < Zero	BLE	2F	3 2									$Z + (N \oplus V) = 1$	•	•	•	•	•	•					
Branch If Lower Or Same	BLS	23	3 2									$C + Z = 1$	•	•	•	•	•	•					
Branch If < Zero	BLT	2D	3 2									$N \oplus V = 1$	•	•	•	•	•	•					
Branch If Minus	BMI	2B	3 2									N = 1	•	•	•	•	•	•					
Branch If Not Equal Zero	BNE	26	3 2									Z = 0	•	•	•	•	•	•					
Branch If Overflow Clear	BVC	28	3 2									V = 0	•	•	•	•	•	•					
Branch If Overflow Set	BVS	29	3 2									V = 1	•	•	•	•	•	•					
Branch If Plus	BPL	2A	3 2									N = 0	•	•	•	•	•	•					
Branch To Subroutine	BSR	8D	5 2										•	•	•	•	•	•					
Jump	JMP					6E	3 2	7E	3 3			See Special Operations	•	•	•	•	•	•					
Jump To Subroutine	JSR			9D	5 2	AD	5 2	BD	6 3				•	•	•	•	•	•					
No Operation	NOP									01	1 1	Advances Prog. Cntr. Only	•	•	•	•	•	•					
Return From Interrupt	RTI									3B	10 1	See Special Operations	③					•	•	•	•	•	•
Return From Subroutine	RTS									39	5 1		•	•	•	•	•	•	•				
Software Interrupt	SWI									3F	12 1		•	S	•	•	•	•	•				
Wait for Interrupt*	WAI									3E	9 1		•	①	•	•	•	•	•				
Sleep	SLP									1A	4 1		•	•	•	•	•	•	•				

Note) *WAI puts R/W high; Address Bus goes to FFFF; Data Bus goes to the three state level.
Condition Register will be explained in Note of Table 11.

Table 11 Condition Code Register Manipulation Instructions

Operations	Mnemonic	Addressing Modes			Boolean Operation	Condition Code Register					
		IMPLIED				5	4	3	2	1	0
		OP	~	#		H	I	N	Z	V	C
Clear Carry	CLC	0C	1	1	0 → C	•	•	•	•	•	R
Clear Interrupt Mask	CLI	0E	1	1	0 → I	•	R	•	•	•	•
Clear Overflow	CLV	0A	1	1	0 → V	•	•	•	•	R	•
Set Carry	SEC	0D	1	1	1 → C	•	•	•	•	•	S
Set Interrupt Mask	SEI	0F	1	1	1 → I	•	S	•	•	•	•
Set Overflow	SEV	0B	1	1	1 → V	•	•	•	•	S	•
Accumulator A → CCR	TAP	06	1	1	A → CCR	⑩					
CCR → Accumulator A	TPA	07	1	1	CCR → A	•	•	•	•	•	•

(NOTE) Condition Code Register Notes: (Bit set if test is true and cleared otherwise)

- ① (Bit V) Test: Result = 10000000?
- ② (Bit C) Test: Result ≠ 00000000?
- ③ (Bit C) Test: BCD Character of high-order byte greater than 10? (Not cleared if previously set)
- ④ (Bit V) Test: Operand = 10000000 prior to execution?
- ⑤ (Bit V) Test: Operand = 01111111 prior to execution?
- ⑥ (Bit N) Test: Set equal to N=C=1 after the execution of instructions
- ⑦ (Bit N) Test: Result less than zero? (Bit 15=1)
- ⑧ (All) Load Condition Code Register from Stack.
- ⑨ (Bit I) Set when interrupt occurs. If previously set, a Non-Maskable Interrupt is required to exist the wait state.
- ⑩ (All Bit) Set according to the contents of Accumulator A.
- ⑪ (Bit C) Result of Multiplication Bit 7=1? (ACCB)

Table 12 OP-Code Map

OP CODE						ACC A	ACC B	IND	EXT DIR	ACCA or SP				ACCB or X							
	HI	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111				
LO		0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F				
1000	0		SBA	BRA	TSX	NEG								SUB				0			
0001	1	NOP	CBA	BRN	INS					AIM					CMP				1		
0010	2			BHI	PULA					OIM					SBC				2		
0011	3				BLS	COM				SUBD				ADDD				3			
0100	4	LSRD			BCC	LSR								AND				4			
0101	5	ASLD			BCS	TXS				EIM				BIT				5			
0110	6	TAP	TAB	BNE	PSHA	ROR								LDA				6			
0111	7	TPA	TBA	BEQ	PSHB	ASR								STA					STA	7	
1000	8	INX	XGDX	BVC	PULX	ASL								EOR				8			
1001	9	DEX	DAA	BVS	RTS	ROL								ADC				9			
1010	A	CLV	SLP	BPL	ABX	DEC								ORA				A			
1011	B	SEV	ABA	BMI	RTI					TIM					ADD				B		
1100	C	CLC		BGE	PSHX	INC								CPX		LDD		C			
1101	D	SEC		BLT	MUL	TST				BSR		JSR						STD	D		
1110	E	CLI		BGT	WAI					JMP		LDS						LDX	E		
1111	F	SEI		BLE	SWI	CLR								STS						STX	F
		0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F				

UNDEFINED OP CODE 

* Only each instructions of AIM, OIM, EIM, TIM

■ LOW POWER CONSUMPTION MODE

The HD6301V0 has two low power consumption modes; sleep and standby mode

● Sleep Mode

On execution of SLP instruction, the MCU is brought to the sleep mode. In the sleep mode, the MPU sleeps (the MPU clock becomes inactive), but the contents of the register in the MPU is secured. In this mode, the peripherals of MPU will remain operational. So the operations such as transmit and receive of

the SCI data and counter may keep on functioning. In this mode, the power consumption is reduced to about 1/10 the value of a normal operation.

The escape from this mode can be done by interrupt, RES, STBY. The RES resets the MCU and the STBY brings it into the standby mode (This will be mentioned later). When interrupt is requested to the MPU and accepted, the sleep mode escapes, then the MPU is brought to the operation mode and vectors to the interrupt routine. When the MPU has masked the interrupt, after releasing from the sleep mode, the next instruction of

HD6301V0, HD63A01V0, HD63B01V0

sleep starts to execute. However, in such a case that the timer interrupt is inhibited on the timer side, the sleep mode cannot be released due to the absence of the interrupt request to the MPU.

This sleep mode is available to reduce an average power consumption in the applications of the HD6301V0 which may not always drive.

Standby Mode

Bringing STBY “Low”, the MPU becomes reset with all clocks of the HD6301V0 inactive and goes into the standby mode. This mode remarkably reduces the power consumptions of the HD6301V0.

In the standby mode, the HD6301V0 is continuously supplied with power so the contents of RAM is retained. The standby mode should escape by the reset start. The following is the typical application of this mode.

First, NMI routine stacks the MCU’s internal information and the contents of SP in RAM, disables RAME bit of RAM control register, sets the STBY bit, and then goes into the standby mode. If the STBY bit keeps set on reset start, it means that the power supply and the contents of RAM is normally guaranteed. The system recovery may be possible by returning SP and bringing into the condition before the standby mode has started. The timing relation for each line in this application is shown in Figure 24.

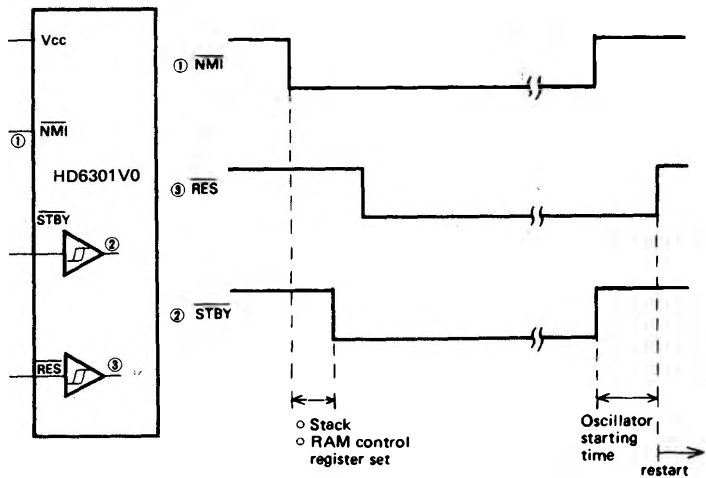


Figure 24 Standby Mode Timing

ERROR PROCESSING

When the HD6301V0 fetches an undefined instruction or fetches an instruction from nonresident memory area, it generates the most precedent internal interrupt, that may protect the system from system burst due to noise or a program error.

Op-Code Error

Fetching an undefined op-code, the HD6301V0 will stack the MPU register as in the case of a normal interrupt and vector to the TRAP (\$FFEE, \$FFEF), that has a second highest priority (RES is the highest).

Address Error

When an instruction is fetched from other than a resident ROM, RAM, or an external memory area, the MPU starts the same interrupt as op-code error. In case where the instruction is fetched from external memory area of non-resident memory, it cannot function.

The addresses which cause address error in particular mode are as shown in Table 13.

This feature is applicable only to the instruction fetch, not to normal read/write of data accessing.

Table 13 Address Error

Mode	0	1	4	5	6	7
	\$0000	\$0000	\$0000	\$0000	\$0000	\$0000
	\$001F	\$001F	\$001F	\$007F	\$001F	\$007F
				\$0200		\$0100
				\$EFFF		\$EFFF

Transitions among the active mode, sleep mode, standby mode and reset are shown in Fig. 25. Figures 26, 27, 28 and 29 shows a system configuration.

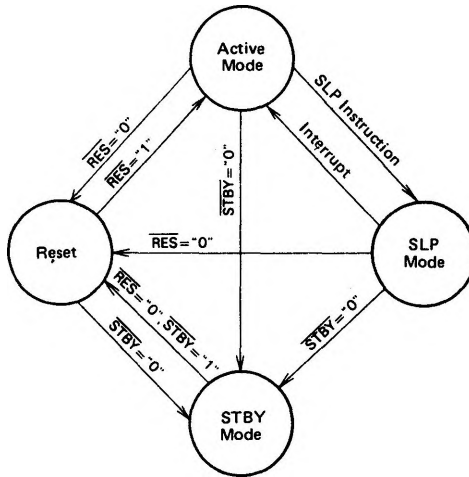


Figure 25 Transitions among Active Mode, Standby Mode Sleep Mode, and Reset

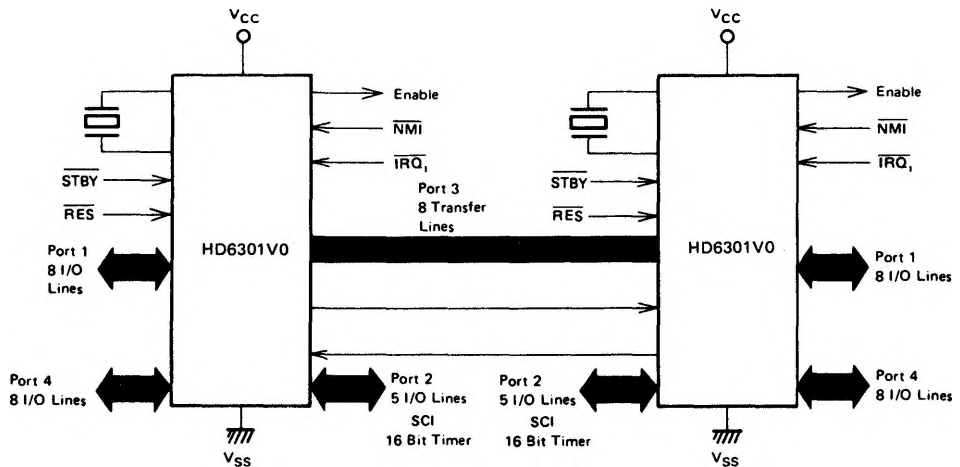


Figure 26 HD6301V0 MCU Single-Chip Dual Processor Configuration

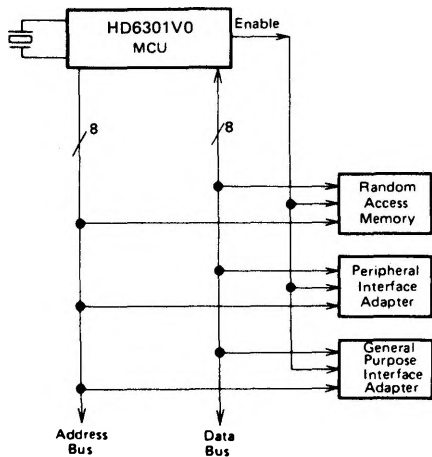


Figure 27 HD6301V0 MCU Expanded Non-Multiplexed Mode (Mode 5)

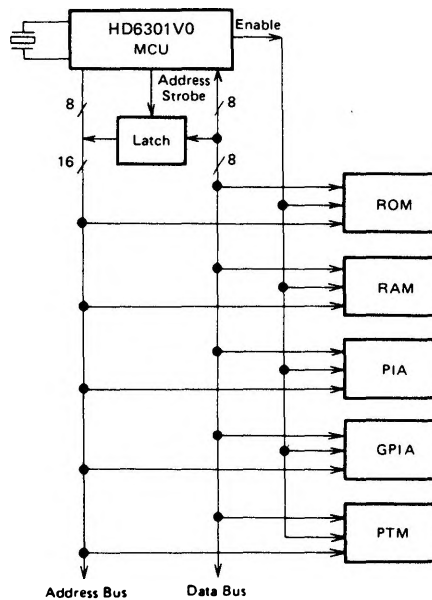


Figure 28 HD6301V0 MCU Expanded Multiplexed Mode

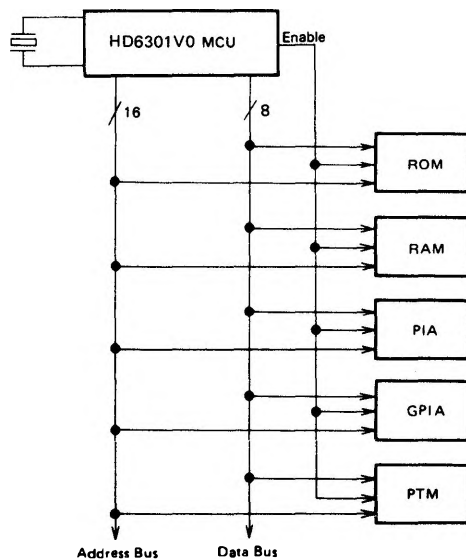


Figure 29 HD6301V0 MCU Expanded Non-Multiplexed Mode (Mode 1)